

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jun Zeng</td> <td>01/07/2012</td> </tr> <tr> <td>Mohamed N. Darwish</td> <td>01/05/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jun Zeng	01/07/2012	Mohamed N. Darwish	01/05/2012						
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Mohamed N. Darwish	01/05/2012												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>MaxPower Semiconductor Inc.</td> </tr> <tr> <td>Street Address:</td> <td>4800 Great America Pkwy.</td> </tr> <tr> <td>Internal Address:</td> <td>Suite 205</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95054</td> </tr> </table>		Name:	MaxPower Semiconductor Inc.	Street Address:	4800 Great America Pkwy.	Internal Address:	Suite 205	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95054
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: (972)419-8329</p> <p>Phone: 214-562-5057</p> <p>Email: cwilkinson@gpm-law.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Robert O. Groover</p> <p>Address Line 1: P. O. Box 293748</p> <p>Address Line 4: Lewisville, TEXAS 75029</p>													
ATTORNEY DOCKET NUMBER:	MXP-013												
NAME OF SUBMITTER:	Robert Groover												
<p>Total Attachments: 3</p> <p>source=ExecutedAssignment#page1.tif</p> <p>source=ExecutedAssignment#page2.tif</p> <p>source=ExecutedAssignment#page3.tif</p>													

CH \$40.00 12368399

ASSIGNMENT

As a below-named inventor of the U.S. patent application entitled SEMICONDUCTOR DEVICE STRUCTURES AND RELATED PROCESSES, with U.S. Application number 12/368,399 , filed February 10, 2009, I hereby sell, assign and transfer to MAXPOWER SEMICONDUCTOR INC. (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title, and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in the United States or any foreign country or national or regional patent authority, for the full term or terms of which the same may be granted, and specifically including the right to file international and foreign national or regional applications and claim priority to this application therefore under the provisions of any convention or treaty;

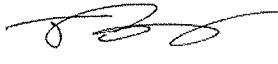
and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and I further hereby covenant that I will, upon ASSIGNEE'S request, promptly provide ASSIGNEE with all pertinent facts and documents, relating to said application, to any invention disclosed therein, or to any of said Letters Patent or legal equivalents thereof in the United States or in foreign countries, as may be known and accessible to me, and that I will testify and give evidence as to the same in any litigation or interference which may arise, and that I will promptly execute and deliver to ASSIGNEE or its legal representative, without charge but at Assignee's expense, any and all papers, instruments or affidavits which may be required, necessary or desirable for the purpose of applying for, obtaining, maintaining, issuing or enforcing said application and said Letters Patent and said equivalents thereof in the United States or in any foreign country; and I further authorize ASSIGNEE or its legal representative to make any submissions or true declarations which may be needed in connection with the prosecution of this application or related applications in the U.S. or in other countries, consistent with the requirements of the applicable country;

AND I HEREBY AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign national or regional patent documents or grants related to this application and/or invention to ASSIGNEE, its successors and assigns.

IN WITNESS WHEREOF, this Assignment has been executed on the date set forth below.

Inventor: JUN ZENG

Signature:  _____ Date: 01/07/2012
Residence: Torrance, California

Inventor: MOHAMED N. DARWISH

Signature: _____ Date: _____
Residence: Campbell, California

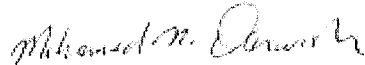
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Inventor: JUN ZENG

Signature: _____ Date: _____
Residence: Torrance, California

Inventor: MOHAMED N. DARWISH



Signature: _____ Date: 1/5/12
Residence: Campbell, California